

02-14-2001

U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

Tab settings

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To the Honorable Commissioner of Patents and Trademarks, attached original documents or copy thereof.

## 1. Name of conveying party(ies):

Masahide Hio

2.5.01

## 2. Name and address of receiving party(ies):

Name: Sumitomo Wiring Systems, Ltd.

Address: 1-14, Nishisuehiro-cho

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

## 3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

City: Yokkaichi-City

State/Prov.: Mie

Country: Japan

ZIP: 510-8503

Execution Date: November 21, 2000

Additional name(s) &amp; address(es)

☐ Yes ☒ No

## 4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is:

Patent Application No.

Filing date

B. Patent No.(s)

09/703,966

November 1, 2000

Additional numbers

☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Gerald E. Hespos

Registration No. 30,066

Address: 274 Madison Avenue - Suite 1703

City: New York

State/Prov.: NY

Country: U.S.A.

ZIP: 10016

## 6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account☐ Authorized to be charged to deposit account

## 8. Deposit account number:

03-1030

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## 9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Gerald E. Hespos

Name of Person Signing

Signature

February 1, 2001

Date

2

Total number of pages including cover sheet, attachments, and

**ASSIGNMENT**

In consideration of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned by the Assignee, Sumitomo Wiring Systems, Ltd., a corporation organized under the laws of Japan, located at 1-14, Nishisuehiro-cho, Yokkaichi-City, Mie, 510-8503 JAPAN, receipt whereof is hereby acknowledged, the undersigned by these presents hereby sells, assigns, transfers and sets over unto the said assignee the entire right, title and interest in and to the invention or improvement entitled "TERMINAL FITTING FOR FLAT CONDUCTOR", said invention being fully described and/or claimed in United States Patent Appl. No. 09/703,966 filed November 1, 2000 in and for the United States, the same to be held and enjoyed by said assignee, its successors, assigns or other legal representatives, to the full ends of the terms for which all Letters Patent therefor may be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

**And Said Assignee Is Hereby Authorized** to make application for and to receive Letters Patent for said invention in any of said countries at its election.

**And By This Covenant The Undersigned** will execute or procure any further necessary assurance of title to said invention and Letters Patent; and at any time, upon the request and at the expense of said assignee, will execute and deliver any and all papers that may be necessary or desirable to perfect the title to said invention or any Letters Patent which may be granted therefor to said Assignee, its successors, assigns or other legal representatives, and, upon the request and at the expense of said assignee, will execute any additional or divisional applications for patents for said invention, or any part or parts thereof, and for the reissue of any Letters Patent to be granted therefor, and will make all rightful oaths and do all lawful acts requisite for procuring the same or for aiding therein, without further compensation, but at the expense of said assignee, its successors, assigns or other legal representatives.

**And The Commissioner Of Patents Is Hereby Authorized And Requested** to issue any and all Letters Patent of the United States for said invention, to said assignee.

Signed and sealed this 21 day of November, 2000.

Masahide Hio L.S.  
Masahide Hio